



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Agarwal et al.

Application No. 10/002,779

Filed: October 29, 2001

For: METHODS FOR FORMING AND INTEGRATED CIRCUIT STRUCTURES

CONTAINING RUTHENIUM AND TUNGSTEN

**CONTAINING LAYERS** 

Examiner: --

Date: August 21, 2002

Art Unit: --

## **CERTIFICATE OF MAILING**

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on August 21, 2002 as First Class Mail in an envelope addressed to: COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

Attorney for Applicant

INFORMATION DISCLOSURE STATEMENT PURSUANT TO 37 C.F.R. § 1.97(b)(3)

COMMISSIONER FOR PATENTS WASHINGTON, DC 20231

Sir:

Listed on the accompanying Form PTO-1449 are several English-language documents.

Applicants respectfully request that these documents be listed as references cited on the issued patent.

Copies of the references listed on the Form PTO-1449 are not enclosed herewith because they were previously cited by or submitted to the Patent Office in a prior application, serial no. 09/590,795, filed on June 8, 2000, which was relied upon in the present application for an earlier filing date under 35 U.S.C. § 120. This Information Disclosure Statement is being filed before the mailing date of a First Office Action on the merits. Thus, according to 37 C.F.R. § 1.97(b)(3), no fee is required. However, if the Patent Office determines that a fee is required for Applicants

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to file this Information Disclosure Statement, please charge any such fees, or credit overpayment, to Deposit Account No. 02-4550. A duplicate copy of this Information Disclosure Statement is enclosed.

Respectfully submitted,

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